# Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment\*

### DIGI-KEY PART # ATS1011-ND

ATS PART # ATS-50350B-C2-R0

#### Features & Benefits

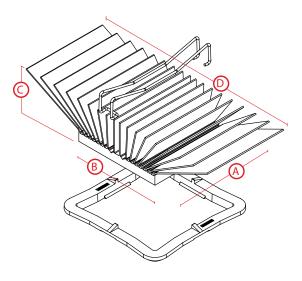
maxiFLOW<sup>™</sup> design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling

maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB

Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards

Comes preassembled with high performance, phase changing, thermal interface material

Designed for standard height components from 3 to 4.5mm





ADVANCED THERMAL

Innovations in Thermal Management®

SOLUTIONS, INC.

#### **Thermal Performance Table AIR VELOCITY** THERMAL RESISTANCE °C/W (DUCTED) FT/MIN M/S °C/W (UNDUCTED) 5.3 200 1.0 3.4 3.9 300 1.5 3.2 400 2.0 2.9 500 2.5 2.6 600 3.0 700 3.5 2.4 800 4.0 2.2

## Product Details<sup>†</sup>

DIMENSION A	DIMENSION B	DIMENSION C <sup>§</sup>	DIMENSION D	TIM <sup>‡</sup>	FINISH
35	35	7.5	44.94	C1100F	BLUE-ANODIZED

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or **www.qats.com** 

\* RoHS Compliant

‡ TIM = Thermal Interface Material

† Dimensions are measured in millimeters
◆ Dimensions A & B refer to component size

 $\$  Dimension C = the height of the heat sink shown above

and does not include the height of the attachment method



